

#### **Features**

- ESD Protection for 1 line with Bi-directional
- Provide ESD protection for the protected line to IEC 61000-4-2 (ESD) ±30kV (air / contact)
   IEC 61000-4-4 (EFT) 80A (5/50ns)
   IEC 61000-4-5 (Lightning) 80A (8/20μs)
- For low operating voltage applications: 2.5V
- DFN package saves board space
- Protect one I/O line or power line
- Fast turn-on and Low clamping voltage
- Solid-state silicon-avalanche and active circuit triggering technology
- Green Part

## **Applications**

- Mobile Phones
- Hand Held Portable Applications
- Computer Interfaces Protection
- Microprocessors Protection
- Serial and Parallel Ports Protection
- Control Signal Lines Protection
- Power lines on PCB Protection
- 2.5V operating systems

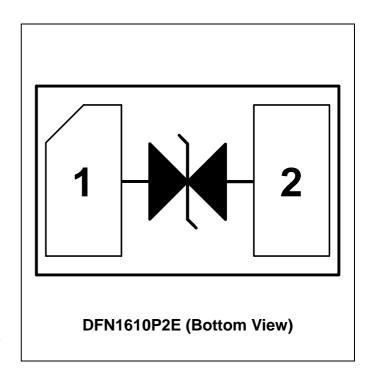
## **Description**

AZ6425-01F is a design which includes one bi-directional surge rated clamping cell to protect one power line, or one control line, or one low speed data line in an electronic systems. The AZ6425-01F has been specifically designed to protect sensitive components which connected to power and control lines from over-voltage damage and latch-up caused by Electrostatic Discharging (ESD), Electrical Fast **Transients** (EFT), Lightning, and Cable Discharge Event (CDE).

AZ6425-01F is a unique design which includes proprietary clamping cell in a single package. During transient conditions, the proprietary clamping cell prevents over-voltage on the power line or control/data lines, protecting any downstream components.

AZ6425-01F may be used to meet the ESD immunity requirements of IEC 61000-4-2, Level 4 (±15kV air, ±8kV contact discharge).

# Circuit Diagram / Pin Configuration



### **SPECIFICATION**

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	RATING	UNITS	
Peak Pulse Current (tp = 8/20μs)	I <sub>PP</sub>	80	А	
Operating Supply Voltage	$V_{DC}$	±2.8	V	
ESD per IEC 61000-4-2 (Air)	V	±30	kV	
ESD per IEC 61000-4-2 (Contact)	$V_{ESD}$	±30		
Lead Soldering Temperature	T <sub>SOL</sub>	260 (10 sec.)	°C	
Operating Temperature	T <sub>OP</sub>	-55 to +85	°C	
Storage Temperature	T <sub>STO</sub>	-55 to +150	°C	

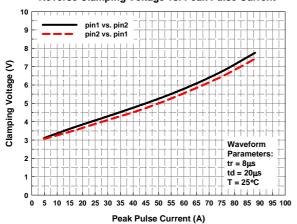
ELECTRICAL CHARACTERISTICS						
PARAMETER	SYMBOL	CONDITIONS	MINI	TYP	MAX	UNITS
Reverse Stand-Off Voltage	$V_{RWM}$	T= 25°C.	-2.5		2.5	V
Reverse Leakage Current	I <sub>Leak</sub>	$V_{RWM} = \pm 2.5 V, T = 25^{\circ}C.$			2	μΑ
Reverse Breakdown Voltage	$V_{BV}$	I <sub>BV</sub> = 1mA, T= 25°C.	3.5			V
Surge Clamping	Clamping V <sub>CL-surge</sub>	$I_{PP} = 5A$ , $tp = 8/20\mu s$ , $T = 25^{\circ}C$ .		3.0		V
Voltage		$I_{PP} = 80A$ , $tp = 8/20\mu s$ , $T = 25^{\circ}C$ .		7.0		V
ESD Clamping Voltage (Note 1)	$V_{\sf clamp}$	IEC 61000-4-2 +8kV (I <sub>TLP</sub> = 16A), Contact mode, T= 25°C.		4.0		V
ESD Dynamic Turn-on Resistance	$R_{\text{dynamic}}$	IEC 61000-4-2 0~+8kV, Contact mode, T= 25 °C.		0.03		Ω
Channel Input Capacitance	$C_{IN}$	$V_R = 0V$ , $f = 1MHz$ , $T=25$ °C.		355	390	pF

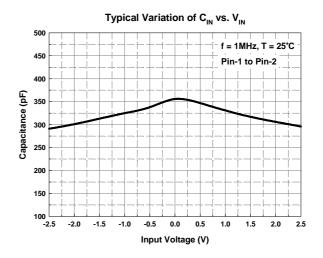
Note 1: ESD Clamping Voltage was measured by Transmission Line Pulsing (TLP) System.

TLP conditions:  $Z_0$ = 50 $\Omega$ ,  $t_p$ = 100ns,  $t_r$ = 1ns.

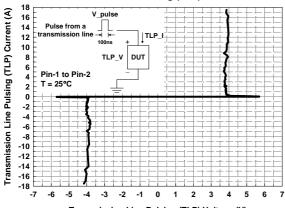
## **Typical Characteristics**

Reverse Clamping Voltage vs. Peak Pulse Current









Transmission Line Pulsing (TLP) Voltage (V)



## **Applications Information**

The AZ6425-01F is designed to protect one line against System ESD/EFT/Surge pulses by clamping them to an acceptable reference. It provides bi-directional protection.

The usage of the AZ6425-01F is shown in Fig. 1. Protected line, such as data line, control line, or power line, is connected at pin 1. The pin 2 is connected to a ground plane on the board. In order to minimize parasitic inductance in the board traces, all path lengths connected to the pins of AZ6425-01F should be kept as short as possible.

In order to obtain enough suppression of ESD induced transient, good circuit board is critical. Thus, the following guidelines are recommended:

- Minimize the path length between the protected lines and the AZ6425-01F.
- Place the AZ6425-01F near the input terminals or connectors to restrict transient coupling.
- The ESD current return path to ground should be kept as short as possible.
- Use ground planes whenever possible.
- NEVER route critical signals near board edges and near the lines which the ESD transient easily injects to.

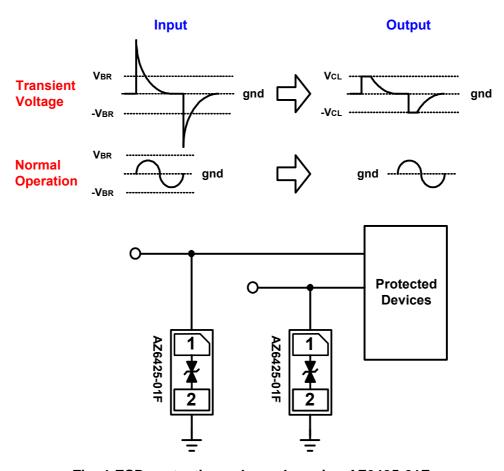
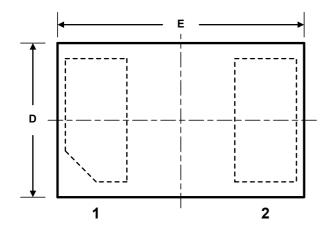


Fig. 1 ESD protection scheme by using AZ6425-01F.

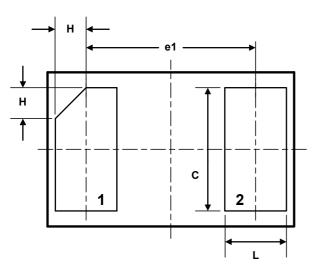


#### **Mechanical Details**

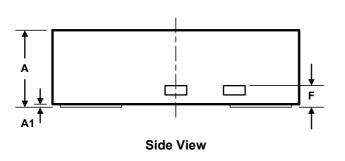
## DFN1610P2E PACKAGE DIAGRAMS



**Top View** 



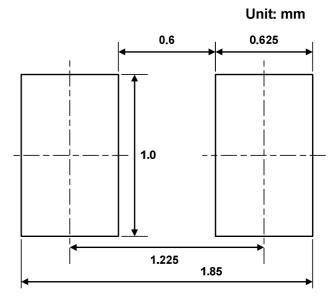
**Bottom View** 



#### PACKAGE DIMENSIONS

SYMBOL	Millimeter			
STWIDUL	Min.	Тур.	Max.	
D	0.95	1.00	1.05	
E	1.55	1.60	1.65	
С	0.75	0.80	0.85	
Α	0.45	0.50	0.55	
<b>A</b> 1	-	0.02	0.05	
e1		1.10BSC		
F	0.10	0.15	0.20	
Н	0.15	0.20	0.25	
L	0.35	0.40	0.45	

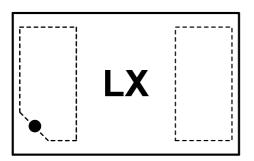
#### **LAND LAYOUT**



#### Notes:

This LAND LAYOUT is for reference purposes only. Please consult your manufacturing partners to ensure your company's PCB design guidelines are met.

#### **MARKING CODE**



**Top View** 

L = Device Code X = Date Code

Part Number	Marking Code		
AZ6425-01F.R7G	ΙX		
(Green Part)	LX		

Note. Green means Pb-free, RoHS, and Halogen free compliant.

## **Ordering Information**

PN#	Material	Type	Reel size	MOQ	MOQ/internal box	MOQ/carton
AZ6425-01F.R7G	Green	T/R	7 inch	3,000/reel	4  reels = 12,000/box	6  boxes = 72,000/carton

# **Revision History**

Revision	Modification Description			
Revision 2016/10/18	Preliminary Release.			
Revision 2017/03/20	Formal Release.			